L Number	Hits	Search Text	DB	Time stamp
1	1168	((438/690) or (438/750) or (438/734) or (438/737)).CCLS.	USPAT;	2004/09/21 13:20
		, , , , , , , , , , , , , , , , , , ,	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	16	US-5164815-\$.DID. OR US-5313102-\$.DID. OR	USPAT;	2004/09/18 19:20
		US-5476566-\$.DID. OR US-5583372-\$.DID. OR	US-PGPUB;	2004/00/10 10:20
		US-0618406-\$.DID. OR US-0624567-\$.DID. OR	EPO; JPO;	
		US-0625819-\$.DID. OR US-0627997-\$.DID. OR	DERWENT:	
		US-6403449-\$.DID. OR US-0650668-\$.DID. OR	IBM_TDB	
]		US-0653441-\$.DID.	IDIVI_IDD	
1_	23		USPAT;	2004/09/18 19:21
-	25	US-5476566-\$.DID. OR US-5583372-\$.DID. OR	US-PGPUB:	2004/03/10 13.21
		US-6184064-\$.DID. OR US-6245677-\$.DID. OR	EPO; JPO;	
		US-6258198-\$.DID. OR US-6279976-\$.DID. OR	DERWENT;	
		US-6403449-\$.DID. OR US-6506681-\$.DID. OR	IBM_TDB	
	60460	US-6534419-\$.DID.	LIODAT	0004/00/40 40 40
-	60162	backside	USPAT;	2004/09/18 19:40
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	4000407		IBM_TDB	0004/00/00 10 ==
-	1632127	chip or die or dice or ic or integrated adj circuit	USPAT;	2004/09/20 18:59
			US-PGPUB;	
			EPO; JPO;	
!			DERWENT;	
ŀ			IBM_TDB	
-	2185088	polymer or epoxy or epoxies or silicone or urethane or siloxane or	USPAT;	2004/09/20 14:46
		parylene	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1929343	coat\$4	USPAT;	2004/09/18 19:44
			US-PGPUB;	
			EPO; JPO;	
Ì			DERWENT;	
			IBM_TDB	
-	293421	cmp or chemical adj mechanical or polish\$4 or planariz\$4 or	USPAT;	2004/09/20 11:42
		planaris\$4	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	backside near4 (chip or die or dice or ic or integrated adj circuit)	USPAT;	2004/09/18 19:46
		near8 coat\$4 near4 (polymer or epoxy or epoxies or silicone or	US-PGPUB;	
		urethane or siloxane or parylene) near6 (cmp or chemical adj	EPO; JPO;	
		mechanical or polish\$4 or planariz\$4 or planaris\$4)	DERWENT;	•
			IBM_TDB	
-	0	backside near4 (chip or die or dice or ic or integrated adj circuit)	USPAT;	2004/09/18 19:47
		same coat\$4 same (polymer or epoxy or epoxies or silicone or	US-PGPUB;	
		urethane or siloxane or parylene) same (cmp or chemical adj	EPO; JPO;	
1		mechanical or polish\$4 or planariz\$4 or planaris\$4)	DERWENT;	
		, , , , , , , , , , , , , , , , , , , ,	IBM_TDB	
-	13	backside near4 (chip or die or dice or ic or integrated adj circuit)	USPAT;	2004/09/20 13:24
		and backside same (polymer or epoxy or epoxies or silicone or	US-PGPUB;	
		urethane or siloxane or parylene) same (cmp or chemical adj	EPO; JPO;	
		mechanical or polish\$4 or planariz\$4 or planaris\$4)	DERWENT;	
		, , , , , , , , , , , , , , , , , , , ,	IBM TDB	
-	8	backside near4 (chip or die or dice or ic or integrated adj circuit)	USPAT;	2004/09/18 20:20
		and backside near8 coat\$4 near8 ((cmp or chemical adj	US-PGPUB;	
		mechanical or polish\$4 or planariz\$4 or planaris\$4) or	EPO; JPO;	
		backgrind\$)	DERWENT;	
			IBM_TDB	
		L	טטו _ואוכו	

-	8	(backside near4 (chip or die or dice or ic or integrated adj circuit)	USPAT;	2004/09/18 20:17
•		and backside near8 coat\$4 near8 ((cmp or chemical adj	US-PGPUB;	
	Ì	mechanical or polish\$4 or planaris\$4 or planaris\$4) or	EPO; JPO;	
	ł	backgrind\$)) not (backside near4 (chip or die or dice or ic or	DERWENT;	
:		integrated adj circuit) and backside same (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) same	IBM_TDB	
		(cmp or chemical adj mechanical or polish\$4 or planariz\$4 or		
		planaris\$4))	,	
_	23		USPAT;	2004/09/18 20:33
		near8 coat\$4 near8 ((cmp or chemical adj mechanical or polish\$4	US-PGPUB;	
		or planariz\$4 or planaris\$4) or backgrind\$)	EPO; JPO;	
			DERWENT;	
•			IBM_TDB	
-	15	1 () 1	USPAT;	2004/09/18 20:20
		near8 coat\$4 near8 ((cmp or chemical adj mechanical or polish\$4	US-PGPUB;	
		or planariz\$4 or planaris\$4) or backgrind\$)) not (backside near4	EPO; JPO;	
		(chip or die or dice or ic or integrated adj circuit) and backside	DERWENT;	
		near8 coat\$4 near8 ((cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4) or backgrind\$))	IBM_TDB	
	6	(chip or die or dice or ic or integrated adj circuit) and backside	USPAT;	2004/09/18 20:30
		near8 passivat\$4 near8 ((cmp or chemical adj mechanical or	US-PGPUB;	2004/03/10 20.30
	1	polish\$4 or planaris\$4 or planaris\$4) or backgrind\$)	EPO; JPO;	
	ŀ	,	DERWENT;	
			IBM_TDB	
-	198	(chip or die or dice or ic or integrated adj circuit) and backside	USPAT;	2004/09/18 20:34
		same coat\$4 same ((cmp or chemical adj mechanical or polish\$4	US-PGPUB;	
ŀ		or planariz\$4 or planaris\$4) or backgrind\$)	EPO; JPO;	ļ
			DERWENT;	
	175	/ (akin an dia an dian ania aniata matada di nimutt) and hantaida	IBM_TDB	0004/00/40 00 00
-	175	((chip or die or dice or ic or integrated adj circuit) and backside same coat\$4 same ((cmp or chemical adj mechanical or polish\$4	USPAT;	2004/09/18 22:08
		or planariz\$4 or planaris\$4) or backgrind\$)) not ((chip or die or	US-PGPUB; EPO; JPO;	
	İ	dice or ic or integrated adj circuit) and backside near8 coat\$4	DERWENT;	
		near8 ((cmp or chemical adj mechanical or polish\$4 or planariz\$4	IBM_TDB	
		or planaris\$4) or backgrind\$))	.5	
-	6		USPAT;	2004/09/18 20:34
		same coat\$4 same ((cmp or chemical adj mechanical or polish\$4	US-PGPUB;	
		or planariz\$4 or planaris\$4) or backgrind\$)).ab.	EPO; JPO;	
i			DERWENT;	
	2105000	nolymor or analysis or alliants at weathers as all and	IBM_TDB	0004/00/40 00 00
-	2185088	polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene	USPAT; US-PGPUB;	2004/09/18 22:09
		Particilo	EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
-	1300622	peaks or valleys or hill or hillocks or rough\$4 or jagged or uneven	USPAT;	2004/09/18 22:54
			US-PGPUB;	
			EPO; JPO;	
]	Į.		DERWENT;	
	400040-		IBM_TDB	
-	1632127	chip or die or dice or ic or integrated adj circuit	USPAT;	2004/09/18 22:20
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	293421	cmp or chemical adj mechanical or polish\$4 or planariz\$4 or	USPAT;	2004/09/18 22:12
		planaris\$4	US-PGPUB;	
			EPO; JPO;	i
			DERWENT;	
	4		IBM_TDB	
-	4042332	smooth\$6 or even\$4	USPAT;	2004/09/18 22:12
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM_TDB	
			מטו ווווסוי	

-	1	(chip or die or dice or ic or integrated adj circuit) and (peaks or	USPAT;	2004/09/18 22:14
		valleys or hill or hillocks or rough\$4 or jagged or uneven) near4	US-PGPUB;	
		(polymer or epoxy or epoxies or silicone or urethane or siloxane	EPO; JPO;	
		or parylene) near6 (cmp or chemical adj mechanical or polish\$4	DERWENT;	
1	404	or planariz\$4 or planaris\$4) near6 (smooth\$6 or even\$4)	IBM_TDB	0004/00/40 00:40
-	161	(chip or die or dice or ic or integrated adj circuit) and (peaks or	USPAT;	2004/09/18 22:13
		valleys or hill or hillocks or rough\$4 or jagged or uneven) same	US-PGPUB;	
		(polymer or epoxy or epoxies or silicone or urethane or siloxane	EPO; JPO;	
		or parylene) same (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4) same (smooth\$6 or even\$4)	DERWENT; IBM_TDB	
	14		USPAT;	2004/09/18 22:19
1-	'-	valleys or hill or hillocks or rough\$4 or jagged or uneven) near4	US-PGPUB;	2004/09/10 22.19
		(polymer or epoxy or epoxies or silicone or urethane or siloxane	EPO; JPO;	
		or parylene) near6 (cmp or chemical adj mechanical or polish\$4	DERWENT;	
		or planariz\$4 or planaris\$4)	IBM TDB	
1_	1632127	chip or die or dice or ic or integrated adj circuit	USPAT:	2004/09/18 22:20
	1002127	crip of the of the of integrated adjustedit	US-PGPUB;	2004/03/10 22.20
		•	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	(chip or die or dice or ic or integrated adj circuit) and sacrificial\$4	USPAT;	2004/09/18 22:43
		near4 (polymer or epoxy or epoxies or silicone or urethane or	US-PGPUB;	
	1	siloxane or parylene) near8 (cmp or chemical adj mechanical or	EPO; JPO;	
		polish\$4 or planariz\$4 or planaris\$4) near4 (smooth\$6 or	DERWENT;	
		even\$4)	IBM_TDB	
-	0	(chip or die or dice or ic or integrated adj circuit) and sacrificial\$4	USPAT;	2004/09/18 22:21
		near8 (polymer or epoxy or epoxies or silicone or urethane or	US-PGPUB;	
		siloxane or parylene) near8 (cmp or chemical adj mechanical or	·EPO; JPO;	
		polish\$4 or planariz\$4 or planaris\$4) same backside	DERWENT;	
			IBM_TDB	4
-	31	(chip or die or dice or ic or integrated adj circuit) and sacrificial\$4	USPAT;	2004/09/18 22:22
		near8 (polymer or epoxy or epoxies or silicone or urethane or	US-PGPUB;	
		siloxane or parylene) near8 (cmp or chemical adj mechanical or	EPO; JPO;	
		polish\$4 or planariz\$4 or planaris\$4)	DERWENT;	
	18	(chip or die or dice or ic or integrated adj circuit) and sacrificial\$4	IBM_TDB USPAT;	2004/09/18 22:46
-	16	near8 (cmp or chemical adj mechanical or polish\$4 or	US-PGPUB;	2004/09/10 22.40
İ	}	planariz\$4 or planaris\$4) near4 (smooth\$6 or even\$4)	EPO; JPO;	
		plananzy+ or plananoy+ / near+ (omodalyo or overly+)	DERWENT;	
			IBM_TDB	
_	18	(chip or die or dice or ic or integrated adj circuit) and sacrificial\$4	USPAT:	2004/09/18 22:52
1		near8 (cmp or chemical adj mechanical or polish\$4 or	US-PGPUB;	
		planariz\$4 or planaris\$4) near4 (smooth\$6 or even\$4)	EPO; JPO;	
	ĺ	, , , , , , , , , , , , , , , , , , , ,	DERWENT;	
]			IBM_TDB	
-	2	20040065554.pn.	USPAT;	2004/09/18 22:47
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
1-	1632127	(chip or die or dice or ic or integrated adj circuit)	USPAT;	2004/09/18 22:52
			US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
	1620407	(abin or die or dies or is or integrated add alexants)	IBM_TDB	2004/00/40 00:50
1-	1632127	(chip or die or dice or ic or integrated adj circuit)	USPAT;	2004/09/18 22:52
			US-PGPUB; EPO; JPO;	
			DERWENT;	
	1		IBM TDB	
_	18	((chip or die or dice or ic or integrated adj circuit)) and	USPAT;	2004/09/18 22:53
		sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4	US-PGPUB;	
		or planariz\$4 or planaris\$4) near4 (smooth\$6 or even\$4)	EPO; JPO;	
		, , , , , , , , , , , , , , , , , , , ,	DERWENT;	
			IBM_TDB	
				·

-	1133	((chip or die or dice or ic or integrated adj circuit)) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4	USPAT; US-PGPUB;	2004/09/18 22:54
		or planariz\$4 or planaris\$4)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1300622	peaks or valleys or hill or hillocks or rough\$4 or jagged or uneven	USPAT;	2004/09/20 11:42
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	12	((chip or die or dice or ic or integrated adj circuit)) and (peaks or	USPAT;	2004/09/18 22:54
		valleys or hill or hillocks or rough\$4 or jagged or uneven) near8	US-PGPUB;	
		sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4	EPO; JPO;	
		or planariz\$4 or planaris\$4)	DERWENT;	
	4000000		IBM_TDB	
-	1300622	peaks or valleys or hill or hillocks or rough\$4 or jagged or uneven	USPAT;	2004/09/20 11:42
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	1632127	chip or die or dice or ic or integrated adj circuit	USPAT;	2004/09/20 11:43
		,	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	0405000		IBM_TDB	0004/00/05
-	2185088	polymer or epoxy or epoxies or silicone or urethane or siloxane or	USPAT;	2004/09/20 11:43
		parylene	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	293421	cmp or chemical adj mechanical or polish\$4 or planariz\$4 or	USPAT;	2004/09/20 11:43
		planaris\$4	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	400		IBM_TDB	0004/00/00 44 45
-	120	(chip or die or dice or ic or integrated adj circuit) and (polymer or	USPAT;	2004/09/20 11:45
		epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4	US-PGPUB; EPO; JPO;	
		or planaris\$4) near8 expos\$4	DERWENT;	
		a promotive of providing the second	IBM_TDB	
-	6	(chip or die or dice or ic or integrated adj circuit) near8 (polymer	USPAT;	2004/09/20 13:18
		or epoxy or epoxies or silicone or urethane or siloxane or	US-PGPUB;	
		parylene) near8 (cmp or chemical adj mechanical or polish\$4 or	EPO; JPO;	
		planariz\$4 or planaris\$4) near8 expos\$4	DERWENT;	
	217	(chip or die or dies or is ar integrated adj sireuit) page? (solumor	IBM_TDB	2004/00/20 16:11
-	217	(chip or die or dice or ic or integrated adj circuit) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or	USPAT; US-PGPUB;	2004/09/20 16:11
		parylene) and (cmp or chemical adj mechanical or polish\$4 or	EPO; JPO;	
		planariz\$4 or planaris\$4) near4 expos\$4	DERWENT;	
		, , , , , , , , , , , , , , , , , , , ,	IBM_TDB	
-	13	(chip or die or dice or ic or integrated adj circuit) near8 (polymer	USPAT;	2004/09/20 13:17
		or epoxy or epoxies or silicone or urethane or siloxane or	US-PGPUB;	
		parylene) near8 (cmp or chemical adj mechanical or polish\$4 or	EPO; JPO;	
		planariz\$4 or planaris\$4) near16 expos\$4	DERWENT;	
_	6	(chip or die or dice or ic or integrated adj circuit) near8 (polymer	IBM_TDB USPAT;	2004/09/20 13:18
	"	or epoxy or epoxies or silicone or urethane or siloxane or	US-PGPUB;	2004/03/20 13.10
ļ		parylene) near8 (cmp or chemical adj mechanical or polish\$4 or	EPO; JPO;	
		planariz\$4 or planaris\$4) near8 expos\$4	DERWENT;	
		<u></u>	IBM_TDB	
-	7	((chip or die or dice or ic or integrated adj circuit) near8 (polymer	USPAT;	2004/09/20 13:18
		or epoxy or epoxies or silicone or urethane or siloxane or	US-PGPUB;	
		parylene) near8 (cmp or chemical adj mechanical or polish\$4 or	EPO; JPO;	
		planariz\$4 or planaris\$4) near16 expos\$4) not ((chip or die or dice or ic or integrated adj circuit) near8 (polymer or epoxy or	DERWENT; IBM_TDB	
		epoxies or silicone or urethane or siloxane or parylene) near8	IDIM_IDB	
		(cmp or chemical adj mechanical or polish\$4 or planariz\$4 or		
		planaris\$4) near8 expos\$4)		
		1:21:00 DM Page 4		

-	8	backside near4 (chip or die or dice or ic or integrated adj circuit)	USPAT;	2004/09/20 13:24
		and backside same (polymer or epoxy or epoxies or silicone or	US-PGPUB;	
		urethane or siloxane or parylene) same (cmp or chemical adj	EPO; JPO;	
		mechanical or polish\$4 or planariz\$4 or planaris\$4) same	DERWENT;	
	4000407	expos\$4	IBM_TDB	0004/00/00 44 47
-	1632127	chip or die or dice or ic or integrated adj circuit	USPAT;	2004/09/20 14:47
			US-PGPUB;	
i			EPO; JPO;	
			DERWENT;	
	2185088	polymer or epoxy or epoxies or silicone or urethane or siloxane or	IBM_TDB USPAT;	2004/09/20 17:38
-	2100000	1	US-PGPUB:	2004/09/20 17:36
	•	parylene	EPO; JPO;	
			DERWENT;	
			IBM TDB	
<u>-</u> .	1414770	sio? or "sio.sub.2" or oxide	USPAT:	2004/09/20 14:49
	1414770	SIO: OF SIO.SUB.2 OF OXIGO	US-PGPUB;	2004/03/20 14.43
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	60162	backside	USPAT;	2004/09/20 14:54
			US-PGPUB;	
			EPO; JPO;	
	}		DERWENT:	
			IBM_TDB	
-	1567914	sio? or "sio.sub.2" or oxide or oxidiz\$4	USPAT;	2004/09/20 14:50
			US-PGPUB;	
			EPO; JPO;	
ĺ			DERWENT;	
			IBM_TDB	
-	2		USPAT;	2004/09/20 14:51
		near4 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near4 (polymer	US-PGPUB;	
		or epoxy or epoxies or silicone or urethane or siloxane or	EPO; JPO;	
		parylene)	DERWENT;	
	4002		IBM_TDB	0004/00/00 44.54
-	1983	expos\$4 near4 backside	USPAT;	2004/09/20 14:51
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	((chip or die or dice or ic or integrated adj circuit) and backside	USPAT;	2004/09/20 14:55
		near4 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near4 (polymer	US-PGPUB;	200 11 00 12 0 1 11 00
		or epoxy or epoxies or silicone or urethane or siloxane or	EPO; JPO;	
	1	parylene)) and (expos\$4 near4 backside)	DERWENT;	
		, , , , , , , , , , , , , , , , , , , ,	IBM_TDB	
-	25	(chip or die or dice or ic or integrated adj circuit) and backside	USPAT;	2004/09/20 17:38
		near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer	US-PGPUB;	
		or epoxy or epoxies or silicone or urethane or siloxane or	EPO; JPO;	
		parylene)	DERWENT;	
-			IBM_TDB	
-	1		USPAT;	2004/09/20 14:52
		near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer	US-PGPUB;	
		or epoxy or epoxies or silicone or urethane or siloxane or	EPO; JPO;	
		parylene)) and (expos\$4 near4 backside)	DERWENT;	
	404	/ohio on dio on dio on io on interpreta die di 1 1/1 1/1 1/1 1/1 1/1 1/1 1/1 1/1 1/1	IBM_TDB	0004/00/00
-	161		USPAT;	2004/09/20 14:54
		same (sio? or "sio.sub.2" or oxide or oxidiz\$4) same (polymer or	US-PGPUB;	
		epoxy or epoxies or silicone or urethane or siloxane or parylene)	EPO; JPO;	
			DERWENT;	
_	179323	backside or bottom adj side or flip adj side or flipside	IBM_TDB	2004/00/20 47:40
-	119323	backside of bottom auj side of hip auj side of hipside	USPAT; US-PGPUB;	2004/09/20 17:40
		·	EPO; JPO;	
			DERWENT;	
	l		IBM_TDB	
	·	L	.5	L

-	20	((chip or die or dice or ic or integrated adj circuit) and backside same (sio? or "sio.sub.2" or oxide or oxidiz\$4) same (polymer or	USPAT; US-PGPUB;	2004/09/20 15:07
		epoxy or epoxies or silicone or urethane or siloxane or parylene))	EPO; JPO;	
	Į.	and (expos\$4 near4 backside)	DERWENT;	
		and (exposure near backside)	IBM TDB	
_	0	("2003/0096507" "2003/0219912").PN.	USPAT	2004/09/20 15:07
_	Ö	("2003/0096507" "2003/0219912").PN.	USPAT	2004/09/20 15:07
_	Ö	6777334.URPN.	USPAT	2004/09/20 15:07
_	2	(("20030096507") or ("20030219912")).PN.	USPAT;	2004/09/20 16:11
		, , , , , , , , , , , , , , , , , , , ,	US-PGPUB	
-	1525	releas\$4 near4 "27" and (chip or die or dice or ic or integrated adj	USPAT;	2004/09/20 16:12
į		circuit)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
İ	200		IBM_TDB	0004/00/00 40:40
-	269	releas\$4 near4 (backside or bottom adj side or flip adj side or	USPAT;	2004/09/20 16:13
		flipside) and (chip or die or dice or ic or integrated adj circuit)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
l <u>.</u>	309631	backside or bottom adj side or (flip or back) adj side or flipside	USPAT;	2004/09/20 16:13
		backetae of backetti aaj alab of (iiip of back) aaj olab of iiipolab	US-PGPUB;	2004/00/20 10:10
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	571771	backside or bottom adj side or (flip or back or under) adj side or	USPAT;	2004/09/20 16:13
		flipside or underside	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	440		IBM_TDB	0004/00/00 40:44
-	142		USPAT;	2004/09/20 16:14
		under) adj side or flipside or underside) same (chip or die or dice or ic or integrated adj circuit)	US-PGPUB;	
		or ic or integrated adjusticult j	EPO; JPO; DERWENT;	
			IBM_TDB	
_	32	(chip or die or dice or ic or integrated adj circuit) and (backside or	USPAT;	2004/09/20 16:49
1		bottom adj side or (flip or back or under) adj side or flipside or	US-PGPUB;	200 1100120 10110
1		underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8	EPO; JPO;	
		(polymer or epoxy or epoxies or silicone or urethane or siloxane	DERWENT;	
į		or parylene)	IBM_TDB	
-	7	((chip or die or dice or ic or integrated adj circuit) and (backside	USPAT;	2004/09/20 16:49
		or bottom adj side or (flip or back or under) adj side or flipside or	US-PGPUB;	
		underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8	EPO; JPO;	
		(polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) not ((chip or die or dice or ic or integrated adj circuit	DERWENT;	
) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4)	IBM_TDB	
1		near8 (polymer or epoxy or epoxies or silicone or urethane or		
		siloxane or parylene))		
-	399333	epoxy or epoxies	USPAT;	2004/09/20 18:59
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	48	() ()	USPAT;	2004/09/20 17:41
		or bottom adj side or flip adj side or flipside) near4 (epoxy or	US-PGPUB;	
		epoxies)	EPO; JPO;	
]			DERWENT; IBM_TDB	
_	0	((chip or die or dice or ic or integrated adj circuit) near4	USPAT;	2004/09/20 17:42
		(backside or bottom adj side or flip adj side or flipside) near4	US-PGPUB;	2007100120 11.42
		(epoxy or epoxies)) and ((expos\$4 or remov\$4) near4 (backside	EPO; JPO;	
		or bottom adj side or flip adj side or flipside) near4 (epoxy or	DERWENT;	
		epoxies))	IBM_TDB	
-	4	(expos\$4 or remov\$4) near4 (backside or bottom adj side or flip	USPAT;	2004/09/20 17:42
		adj side or flipside) near4 (epoxy or epoxies)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
<u> </u>	L		IBM_TDB	

	1 100010=			0004/00/00 04 40
-	1632127	chip or die or dice or ic or integrated adj circuit	USPAT; US-PGPUB;	2004/09/20 21:16
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	399333	epoxy or epoxies	USPAT;	2004/09/20 19:00
	000000	Sport of Sporting	US-PGPUB;	200 1700/20 10:00
	1		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	156266	thermoset\$6 or thermo adj set\$6	USPAT;	2004/09/20 19:00
	1		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	2026815	substrate or wafer	IBM_TDB	2004/00/20 40:00
-	2020013	Substrate of water	USPAT; US-PGPUB;	2004/09/20 19:08
			EPO; JPO;	
			DERWENT:	
;			IBM TDB	
-	4671698	remov\$4 or etch\$4 or expos\$4	USPAT;	2004/09/20 19:18
		, , ,	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
j -	3823		USPAT;	2004/09/20 19:05
		epoxies) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4	US-PGPUB;	
		or etch\$4 or expos\$4) near4 ((chip or die or dice or ic or	EPO; JPO;	
		integrated adj circuit) or (substrate or wafer) or surface)	DERWENT;	
1_	93	(chip or die or dice or ic or integrated adj circuit) and (epoxy or	IBM_TDB USPAT;	2004/09/20 19:09
		epoxies) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4	US-PGPUB;	2004/05/20 15.05
		or etch\$4 or expos\$4) near4 (epoxy or epoxies) near4 ((chip or	EPO; JPO;	
		die or dice or ic or integrated adj circuit) or (substrate or wafer) or	DERWENT;	
		surface)	IBM TDB	
-	1632127	chip or die or dice or ic or integrated adj circuit	USPAT;	2004/09/20 19:08
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	2026815	auhatrata ar wafa-	IBM_TDB	0004/00/00 40-00
•	2020013	substrate or wafer	USPAT; US-PGPUB;	2004/09/20 19:08
	İ		EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
-	169	(epoxy or epoxies) near8 (thermoset\$6 or thermo adj set\$6) and	USPAT;	2004/09/20 19:13
		(remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies) near4	US-PGPUB;	
		((chip or die or dice or ic or integrated adj circuit) or (substrate or	EPO; JPO;	
]]	wafer) or surface)	DERWENT;	
	l !		IBM_TDB	
-	55	[\	USPAT;	2004/09/20 19:19
		(remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies) near4 expos\$4 near4 ((chip or die or dice or ic or integrated adj circuit)	US-PGPUB;	
		or (substrate or wafer) or surface)	EPO; JPO; DERWENT;	
		O. (Substitute of maior) of surrace)	IBM_TDB	
-	4003371	remov\$4 or etch\$4	USPAT;	2004/09/20 19:18
	1		US-PGPUB;	
			EPO; JPO;	
[DERWENT;	
			IBM_TDB	
-	4120690	remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4	USPAT;	2004/09/20 19:18
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM_TDB	
LI	L	L	מטו_ואוסו	

-	14	(epoxy or epoxies) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4) near4 (epoxy or epoxies) near4 expos\$4 near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/20 19:36
-	64	(remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4) near4 (epoxy or epoxies) near4 expos\$4 near4 ((substrate or wafer) or	IBM_TDB USPAT; US-PGPUB;	2004/09/20 19:40
		surface)	EPO; JPO; DERWENT; IBM_TDB	
•	12	((remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4) near4 (epoxy or epoxies) near4 expos\$4 near4 ((substrate or wafer) or surface)) and (thermoset\$6 or thermo adj set\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/20 19:38
-	1	(((remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4) near4 (epoxy or epoxies) near4 expos\$4 near4 ((substrate or wafer) or surface)) and (thermoset\$6 or thermo adj set\$6)) not ((epoxy or epoxies) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4) near4 (epoxy or epoxies) near4 expos\$4 near4 ((chip or die or dice or ic or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:38
-	53	integrated adj circuit) or (substrate or wafer) or surface)) ((remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4) near4 (epoxy or epoxies) near4 expos\$4 near4 ((substrate or wafer) or surface)) not ((epoxy or epoxies) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4) near4 (epoxy or epoxies) near4 expos\$4 near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:24
-	20672	(thermoset\$6 or thermo adj set\$6) near4 (epoxy or epoxies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:24
-	215	(epoxy or epoxies) near4 (screen or stencil or spin) near coat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/20 20:25
-	0	partial\$4 near2 (cur\$4 or set\$6 or harden\$4) near4 (epoxy or epoxies) near4 (before or subsequent\$4) near4 apply\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:28
•	865	partial\$4 near2 (cur\$4 or set\$6 or harden\$4) near4 (epoxy or epoxies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/20 20:29
-	3	((thermoset\$6 or thermo adj set\$6) near4 (epoxy or epoxies)) and ((epoxy or epoxies) near4 (screen or stencil or spin) near coat\$4) and (partial\$4 near2 (cur\$4 or set\$6 or harden\$4) near4 (epoxy or epoxies)) and ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/20 20:37
-	42	partial\$4 near2 (cur\$4 or set\$6 or harden\$4) near4 (epoxy or epoxies) near4 (before or subsequent\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:32
-	2	tacky near4 (epoxy or epoxies) near4 (before or subsequent\$4) near4 (coat\$4 or apply\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/20 20:39

-	144	(epoxy or epoxies) near4 (cur\$4 or harden\$4 or set\$6) near4 (before or subsequent\$4) near4 (coat\$4 or apply\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/20 20:34
			IBM_TDB	
1_	O	((epoxy or epoxies) near4 (cur\$4 or harden\$4 or set\$6) near4	USPAT;	2004/09/20 20:39
		(before or subsequent\$4) near4 (coat\$4 or apply\$4)) and ((epoxy	US-PGPUB;	200 1100/20 20100
		or epoxies) near4 (screen or stencil or spin) near coat\$4) and	EPO; JPO;	
		((chip or die or dice or ic or integrated adj circuit) or (substrate or	DERWENT;	
		wafer))	IBM_TDB	
-	14		USPAT;	2004/09/20 20:40
		subsequent\$4) near4 (coat\$4 or apply\$4)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	0	((epoxy or epoxies) near4 (hardener) near4 (before or	USPAT;	2004/09/20 20:40
	1	subsequent\$4) near4 (coat\$4 or apply\$4)) and ((epoxy or epoxies	US-PGPUB;	
]) near4 (screen or stencil or spin) near coat\$4) and ((chip or die	EPO; JPO;	
		or dice or ic or integrated adj circuit) or (substrate or wafer))	DERWENT;	
	10202	(onesa or enevine) poer4 (herdener)	IBM_TDB	2004/00/20 20:40
-	10282	(epoxy or epoxies) near4 (hardener)	USPAT; US-PGPUB;	2004/09/20 20:40
1			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
-	5	((epoxy or epoxies) near4 (hardener)) and ((epoxy or epoxies)	USPAT;	2004/09/20 20:59
		near4 (screen or stencil or spin) near coat\$4) and ((epoxy or	US-PGPUB;	
		epoxies) or thermal\$4 or heat\$4) near4 (epoxy or epoxies)	EPO; JPO;	
			DERWENT; IBM_TDB	
-	223	tape same releas\$4 near2 (film or layer) same backing and (chip	USPAT:	2004/09/20 21:01
		or die or dice or ic or integrated adj circuit)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	21	tape near8 releas\$4 near2 (film or layer) near8 backing same	IBM_TDB USPAT;	2004/09/20 21:09
		(chip or die or dice or ic or integrated adj circuit)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	256	tone nearly released a nearly (film or levery) nearly backing	IBM_TDB	2004/09/20 21:09
-	256	tape near8 releas\$4 near2 (film or layer) near8 backing	USPAT; US-PGPUB;	2004/09/20 21:09
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	152599	(chip or die or dice or ic or integrated adj circuit) near4 (substrate	USPAT;	2004/09/20 21:12
]	or wafer)	US-PGPUB;	
			EPO; JPO; DERWENT;	
]		IBM_TDB	
-	3	(tape near8 releas\$4 near2 (film or layer) near8 backing) and	USPAT;	2004/09/20 21:14
		((chip or die or dice or ic or integrated adj circuit) near4	US-PGPUB;	
		(substrate or wafer))	EPO; JPO;	
			DERWENT; IBM_TDB	
_	168580	((chip or die or dice or ic or integrated adj circuit) or packag\$4)	USPAT;	2004/09/20 21:14
		near4 (substrate or wafer)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	11	(tang near released near) (film or layer) near hacking) and	IBM_TDB	2004/00/20 24:45
1	''	((chip or die or dice or ic or integrated adj circuit) or packag\$4)	USPAT; US-PGPUB;	2004/09/20 21:15
		near4 (substrate or wafer))	EPO; JPO;	
		· "	DERWENT;	
L			IBM_TDB	

-	101	(chip or die or dice or ic or integrated adj circuit) near4 (backing	USPAT;	2004/09/20 21:17
		near4 tap\$4)	US-PGPUB;	
			EPO; JPO;	
•			DERWENT;	
			IBM TDB	
-	4	(tape same releas\$4 near2 (film or layer) same backing and (chip	USPAT;	2004/09/20 21:17
		or die or dice or ic or integrated adj circuit)) and ((chip or die or	US-PGPUB:	
		dice or ic or integrated adj circuit) near4 (backing near4 tap\$4))	EPO: JPO:	
			DERWENT:	
			IBM TDB	